## MMSD914T1G, SMMSD914T1G, MMSD914T3G

# **Switching Diode**

#### **Features**

- SOD-123 Surface Mount Package
- High Breakdown Voltage
- Fast Speed Switching Time
- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant\*

### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V <sub>R</sub>	100	Vdc
Peak Forward Current	I <sub>F</sub>	200	mAdc
Peak Forward Surge Current	I <sub>FM(surge)</sub>	500	mAdc
Non-repetitive Peak Forward Surge Current Pulse Width =1 second Pulse Width =1 micro second	I <sub>FSM</sub>	1.0 2.0	A A

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1)  T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	425 3.4	mW mW/°C
Derate above 23 C		3.4	· ·
Thermal Resistance, Junction-to-Ambient	$R_{ heta JA}$	290	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

1. FR-5 = 1.0oz Cu, 1.0in<sup>z</sup> pad



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SOD-123 CASE 425 PLASTIC



### **MARKING DIAGRAM**



5D = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMSD914T1G	SOD-123 (Pb-Free)	3,000 / Tape & Reel
SMMSD914T1G	SOD-123 (Pb-Free)	3,000 / Tape & Reel
MMSD914T3G	SOD-123 (Pb-Free)	10,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

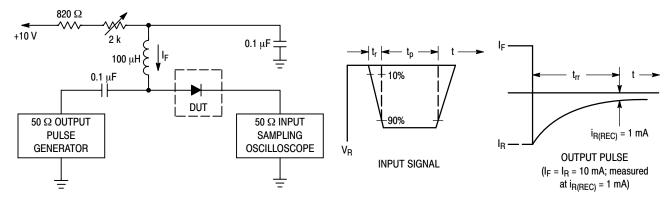
1

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## MMSD914T1G, SMMSD914T1G, MMSD914T3G

### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic		Min	Max	Unit		
OFF CHARACTERISTICS						
Reverse Breakdown Voltage (I <sub>BR</sub> = 100 μAdc)		100	-	Vdc		
Reverse Voltage Leakage Current $(V_R = 20 \text{ Vdc})$ $(V_R = 75 \text{ Vdc})$	I <sub>R</sub>	- -	25 5.0	nAdc μAdc		
Forward Voltage (I <sub>F</sub> = 10 mAdc)	V <sub>F</sub>	-	1000	mVdc		
Diode Capacitance (V <sub>R</sub> = 0 Vdc, f = 1.0 MHz)	C <sub>D</sub>	-	4.0	pF		
Reverse Recovery Time (I <sub>F</sub> = I <sub>R</sub> = 10 mAdc) (Figure 1)	t <sub>rr</sub>	_	4.0	ns		

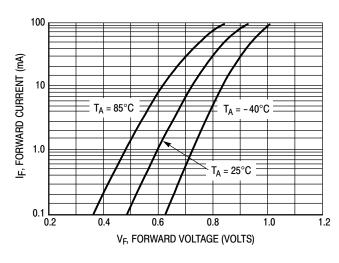


Notes: 1. A 2.0  $k\Omega$  variable resistor adjusted for a Forward Current (IF) of 10 mA.

- 2. Input pulse is adjusted so I<sub>R(peak)</sub> is equal to 10 mA.
- 3. t<sub>p</sub> » t<sub>rr</sub>

Figure 1. Recovery Time Equivalent Test Circuit

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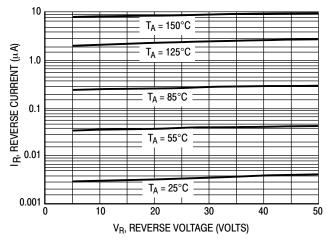


Figure 2. Forward Voltage

Figure 3. Leakage Current

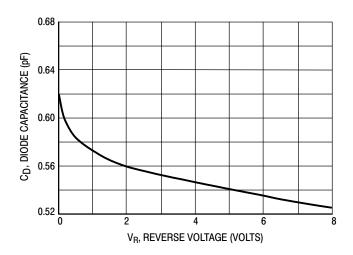
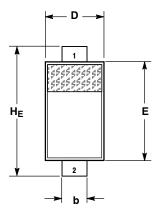


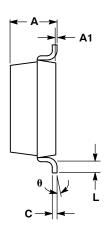
Figure 4. Capacitance

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#### PACKAGE DIMENSIONS

**SOD-123** CASE 425-04 ISSUE G





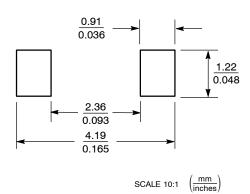
#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.94	1.17	1.35	0.037	0.046	0.053
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.51	0.61	0.71	0.020	0.024	0.028
C			0.15			0.006
D	1.40	1.60	1.80	0.055	0.063	0.071
E	2.54	2.69	2.84	0.100	0.106	0.112
HE	3.56	3.68	3.86	0.140	0.145	0.152
L	0.25			0.010		
θ	0°		10°	0°		10°

STYLE 1: PIN 1. CATHODE 2 ANODE

### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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